

**2SA1737**

## Silicon PNP epitaxial planer type

For video amplifier

## ■ Features

- High transition frequency  $f_T$ .
- Small collector output capacitance  $C_{ob}$ .
- Mini Power type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

## ■ Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	-85	V
Collector to emitter voltage	$V_{CEO}$	-85	V
Emitter to base voltage	$V_{EBO}$	-4	V
Peak collector current	$I_{CP}$	-100	mA
Collector current	$I_C$	-50	mA
Collector power dissipation	$P_C^*$	1	W
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	-55 ~ +150	°C

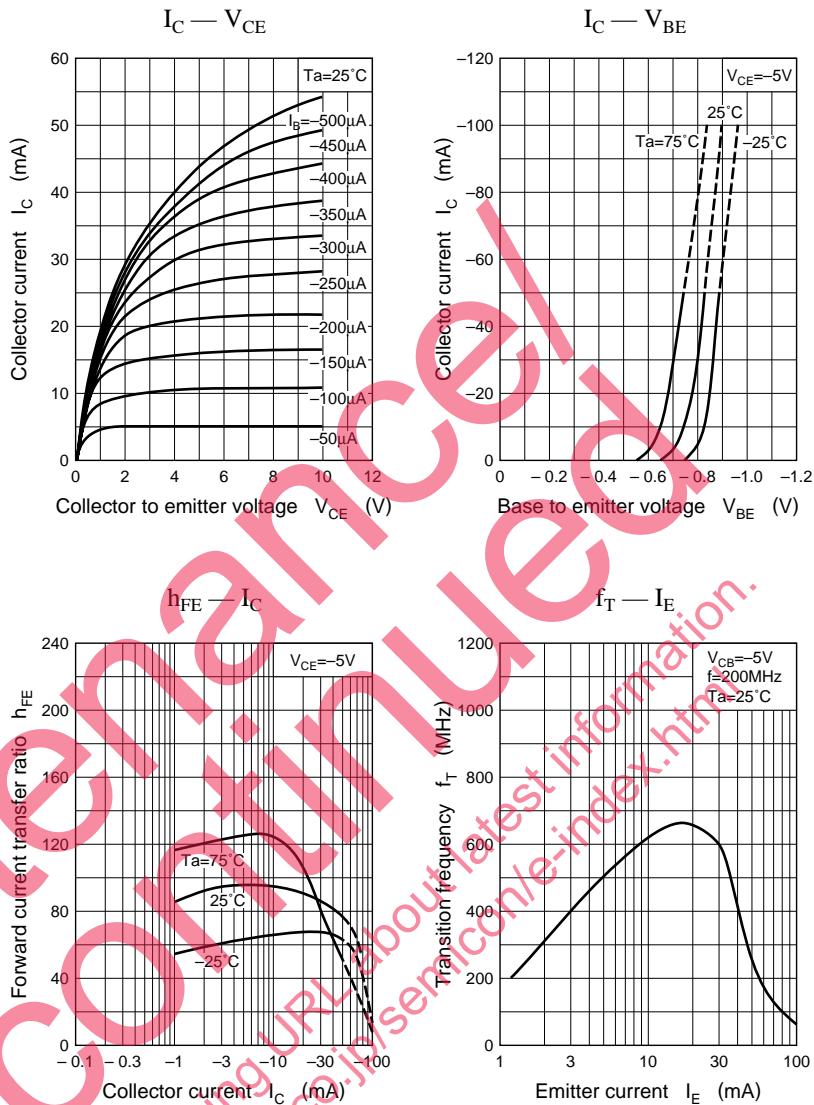
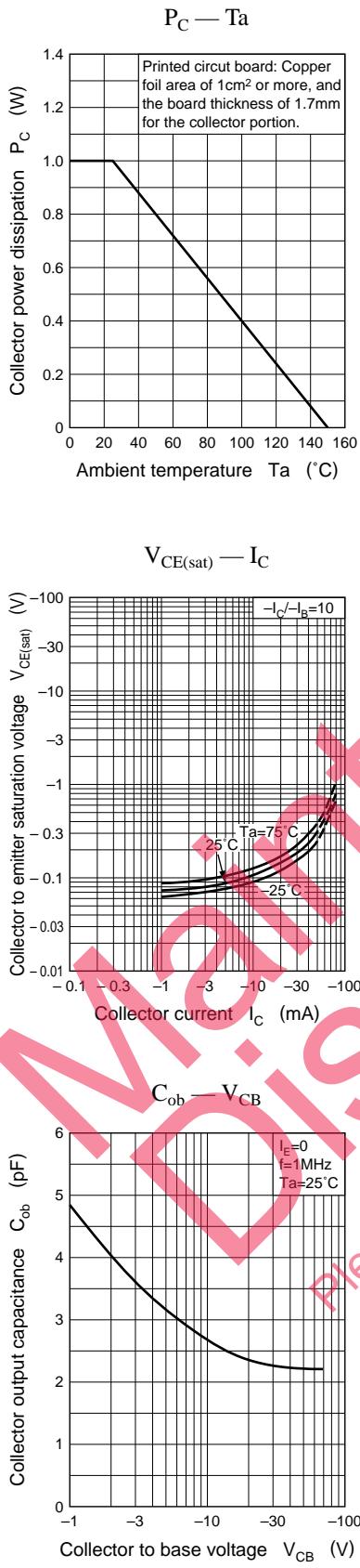
\* Printed circuit board: Copper foil area of 1cm<sup>2</sup> or more, and the board thickness of 1.7mm for the collector portion

#### ■ Electrical Characteristics (Ta=25°C)



Marking symbol : 1E

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	$I_{CEO}$	$V_{CE} = -60V, I_B = 0$			-10	$\mu A$
Collector to base voltage	$V_{CBO}$	$I_C = -100\mu A, I_E = 0$	-85			V
Collector to emitter voltage	$V_{CEO}$	$I_C = -1mA, I_B = 0$	-85			V
Emitter to base voltage	$V_{EBO}$	$I_E = -100\mu A, I_C = 0$	-4			V
Forward current transfer ratio	$h_{FE}$	$V_{CE} = -5V, I_C = -10mA$	60			
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = -10mA, I_B = -1mA$			-0.5	V
Transition frequency	$f_T$	$V_{CB} = -5V, I_E = 10mA, f = 200MHz$	500			MHz
Collector output capacitance	$C_{ob}$	$V_{CB} = -10V, I_E = 0, f = 1MHz$	2.7			pF



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